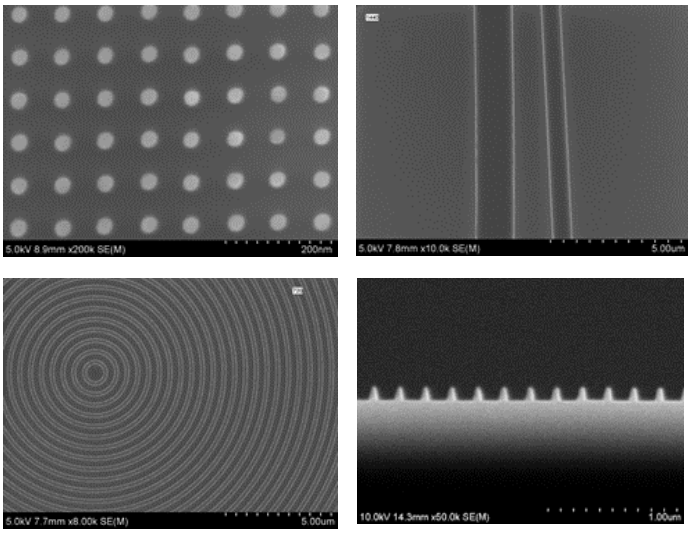
DisChem
CHEMISTRY FOR ADVANCED LITHOGRAPHY

RESIST MATERIALS

H-SiQ



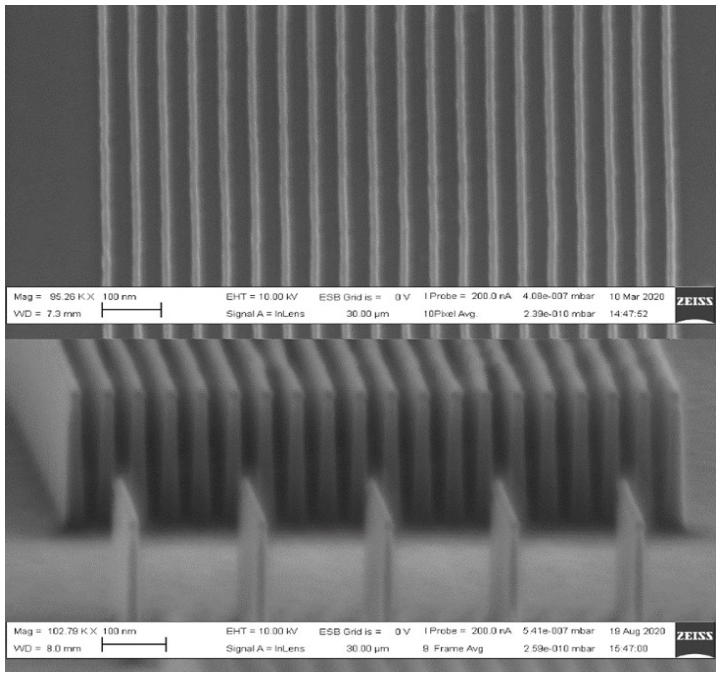
Negative Tone EBL Resist

Hydrogen Silesquioxane (HSQ)

DisChem H-SiQ is a negative tone hydrogen silesquioxane resist derived from dry silicone resin (H-SiOx) in MIBK carrier solvent for use in electron beam lithography (EBL).

H-SiQ is characterized by excellent pitch resolution, sensitivity and etch resistance for direct write thin film EBL applications.

- H-SiQ is prepared on a percent by weight basis of HSQ silicone resin in semiconductor grade MIBK.
- Concentrations ranging from 1 – 30 % for film thicknesses 25—850 nm.
- Ready to use. Immediate availability with 100% shelf life.



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